

L Number	Hits	S arch Text	DB	Time stamp
9	2489	235/487.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 17:22
10	3808	(substrate and (reticle or reticule)) and transfer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 17:22
11	1659	430/22.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 17:22
12	158	355/97.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 17:22
13	0	250/571.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 17:23
14	3	(conveying or conveyor) same scan\$4 same (wafer\$1) same code\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 17:23
15	3	(conveying or conveyor) same scan\$4 same (wafer\$1) same code\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 17:23
16	9	semiconductor same exposure same barcode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 17:48
17	2	6,618,640	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 18:01
18	4	("4833306" "6303398" "6446022" "6507765").PN.	USPAT	2004/04/16 17:49

19	3	4010355.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 18:01
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